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### Supplementary Materials for

## Ultrahigh areal number density solid-state on-chip microsupercapacitors via electrohydrodynamic jet printing

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#### The PDF file includes:

Fig. S1. Basic characteristics of nAC.

Fig. S2. Characteristics of the electrode ink with and without CMC binder.

Fig. S3. Process description of the EHD jet printing for the fabrication of interdigitated electrodes.

Fig. S4. Characterization of the EHD jet-printed electrodes as a function of printing cycles.

Fig. S5. EHD jet printing of the electrolyte ink.

Fig. S6. Characteristics of the solid-state gel electrolytes.

Fig. S7. Photographs showing contact angle change and effect on the affinity between the electrolyte ink and SiO<sub>2</sub>/Si chip substrate.

Fig. S8. Configuration and electrochemical performance of the SS-MSC.

Fig. S9. Schematic representation of the five SS–MSCs.

Table S1. Comparison in the major characteristics between the on-chip UHD SS–MSCs (this study) and the previously reported MSCs fabricated by printing techniques.

Legends for movies S1 and S2

References (37–40)

#### Other Supplementary Material for this manuscript includes the following:

(available at advances.sciencemag.org/cgi/content/full/6/10/eaaz1692/DC1)

Movie S1 (.mp4 format). Video clip showing the fabrication of interdigitated electrodes on top of the SiO<sub>2</sub>/Si chip substrate through the EHD jet printing.

Movie S2 (.mp4 format). Video clip showing the fabrication of solid-state gel electrolytes on top of interdigitated electrodes-deposited SiO<sub>2</sub>/Si chip substrate through the EHD jet printing.

#### **Supplementary Materials**



**Fig. S1. Basic characteristics of nAC. (a)** Particle size distribution. (b) Nitrogen gas adsorption-desorption isotherms at 77K.



**Fig. S2.** Characteristics of the electrode ink with (a,b) and without (c-e) CMC binder. (a) Viscosity as a function of shear rate. (b) Summary of other major physical properties. (c) Photograph. (d) Zeta potential profile. (e) Viscosity as a function of shear rate. Photo credits: (c) Kwon-Hyung Lee, Ulsan National Institute of Science and Technology.



**Fig. S3. Process description of the EHD jet printing for the fabrication of interdigitated electrodes. (a)** Schematic representation of the EHD jet-printing equipment. (b) The pulse DC signal as a function of time. (b) Summary of the optimized process parameters for the EHD jet-printed electrode.







**Fig. S5. EHD jet printing of the electrolyte ink.** (a) Viscosity of the electrolyte ink (*i.e.*, before UV curing) as a function of shear rate. (b) Summary of the optimized process parameters for the electrolyte preparation.



**Fig. S6. Characteristics of the solid-state gel electrolytes.** (a) Viscoelastic properties (G' and G") of the electrolyte ink (*i.e.*, before UV irradiation) and solid-state gel electrolyte (after UV irradiation) at an oscillation frequency 0.1 Hz. (b) CV profiles (scan rate: 20 mV s<sup>-1</sup>) of the model cells: solid-state gel electrolyte vs. liquid electrolyte ([EMIM][TFSI] alone). (c) Change in the weight and ionic conductivity and (d) photographs upon exposure to vacuum state (pressure <  $10^{-2}$  Pa) as a function of vacuum time. Photo credits: (d) Kwon-Hyung Lee, Ulsan National Institute of Science and Technology.



**Fig. S7.** Photographs showing contact angle change and effect on the affinity between the electrolyte ink and SiO<sub>2</sub>/Si chip substrate. (a,c) Pristine SiO<sub>2</sub>/Si chip substrate. (b,d) UVO-treated SiO<sub>2</sub>/Si chip substrate.



Fig. S8. Configuration (a,b) and electrochemical performance (c-e) of the SS–MSC. (a) Schematic representation. (b) Dimension values as a function of electrode width. (c) Comparison of the CV profiles (scan rate: 50 mV s<sup>-1</sup>): SS–MSC vs. bare Ti/Au current collector. (d–e) GCD profiles of the SS–MSC at varied current densities of  $1.30 \sim 27.78 \ \mu A \ cm^{-2}$ .



**Fig. S9. Schematic representation of the five SS–MSCs. (a)** In-series connection. (b) In-parallel connection.

Table S1. Comparison in the major characteristics between the on-chip UHD SS–MSCs (this study) and the previously reported MSCs fabricated by printing techniques.

Fabrication technique	Feature size (µm)	# of cells (n)	Unit cell area (cm <sup>2</sup> )	Cell-to-cell distance (mm)	Cell voltage (V)	Areal-number- density of cells (cells cm <sup>-2</sup> )	Areal- operating-voltage (V cm <sup>-2</sup> )	Reference
EHD printing	<u>10</u>	<u>36</u>	0.0127	<u>0.22</u>	<u>43.2</u>	<u>54.9</u>	<u>65.9</u>	This study
Inkjet printing/ electrodeposition	35	3	N/A	N/A	3.2	0.84*	0.89*	[16]
Inkjet printing	50	2	2*	N/A	1.6	1**	0.8**	[18]
Inkjet printing	300	2	1.2	12*	1.8	0.51*	0.46	[20]
Inkjet printing	300*	5	0.86*	0.5*	10	1.26*	2.7*	[22]
Inkjet printing	300	144	0.2*	0.85*	12	3.16*	0.40*	[37]
Inkjet printing	1000	4	3	N/A	3.2	0.33**	0.26**	[17]
3D printing	250	1	N/A	N/A	1.0	N/A	N/A	[38]
3D printing	250	1	N/A	N/A	0.8	N/A	N/A	[39]
Screen printing	600	130	29.1	7.5*	104	$1.08^{*}$	0.87*	[40]

N/A: Not available.

\* These values were obtained using an image analysis technique.

\*\* Normalized values based on unit cell area.

Movie S1. Video clip showing the fabrication of interdigitated electrodes on top of the SiO<sub>2</sub>/Si chip substrate through the EHD jet printing.

Movie S2. Video clip showing the fabrication of solid-state gel electrolytes on top of interdigitated electrodes-deposited  $SiO_2/Si$  chip substrate through the EHD jet printing.

\*Note that all movies are playing four times faster than real-time for readers' better understanding.